

Title: "FILM DEPOSITION TO ENHANCE SEALING YIELD OF
MICROCAP WAFER-LEVEL PACKAGE WITH VIAS"

Inventors: Qing Gan et al.

Docket no.: 10030302-1

1/5

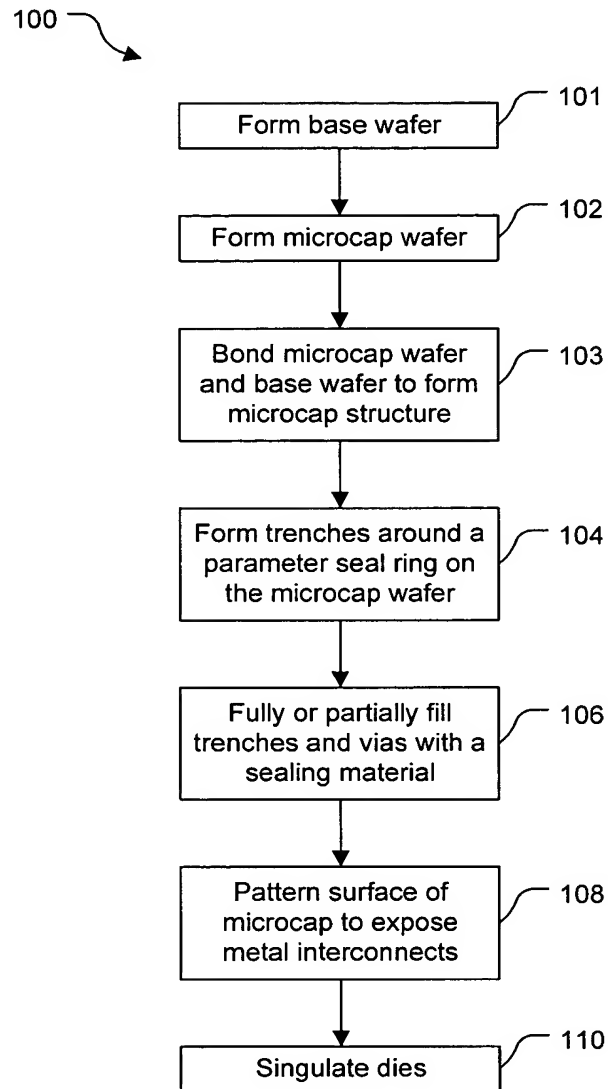


Fig. 1

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2/5

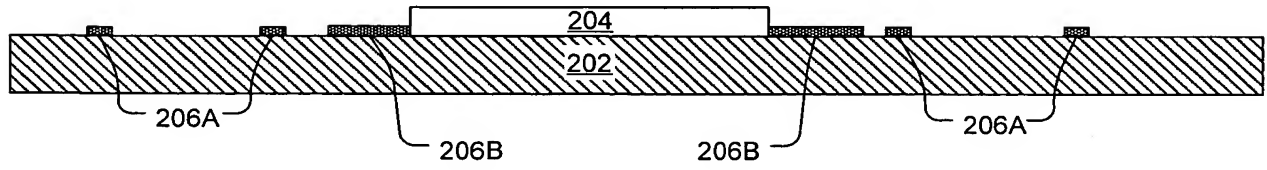


Fig. 2A

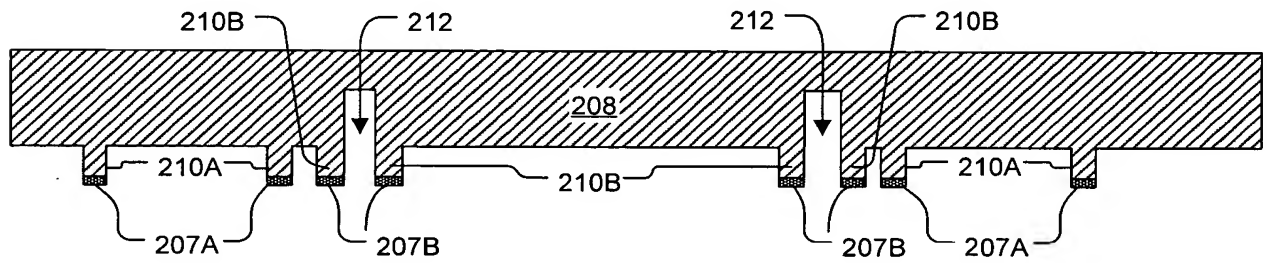


Fig. 2B

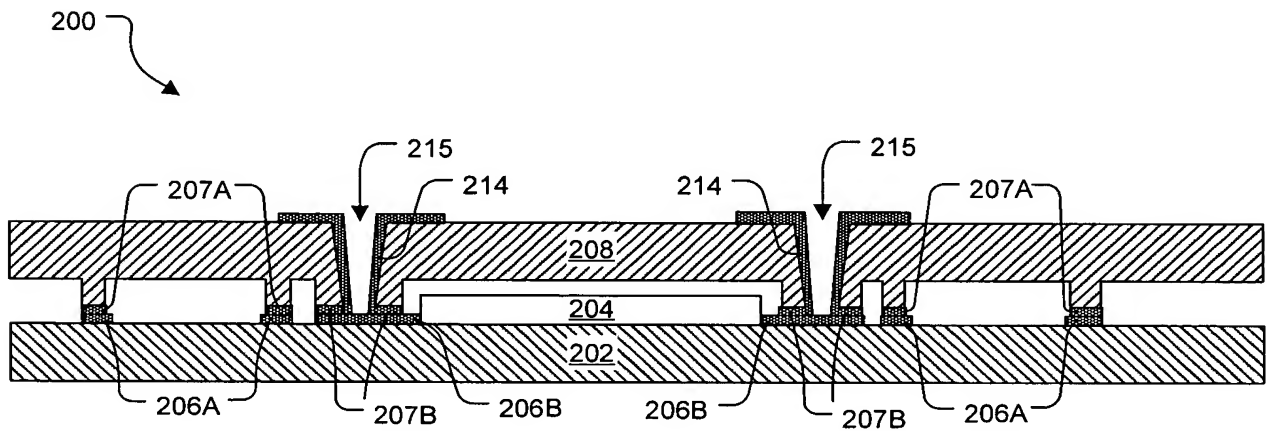


Fig. 2C

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Docket no.: 10030302-1

3/5

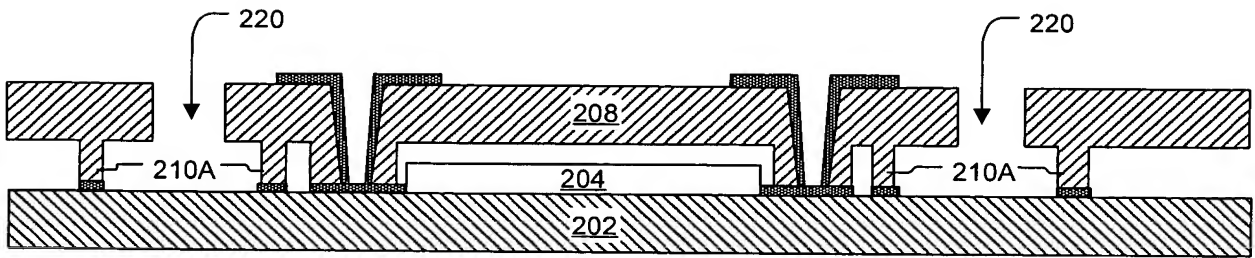


Fig. 3

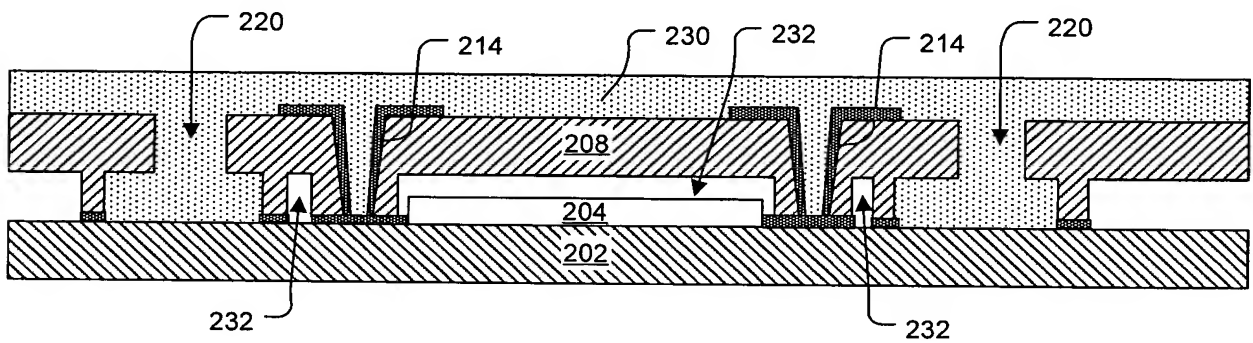


Fig. 4

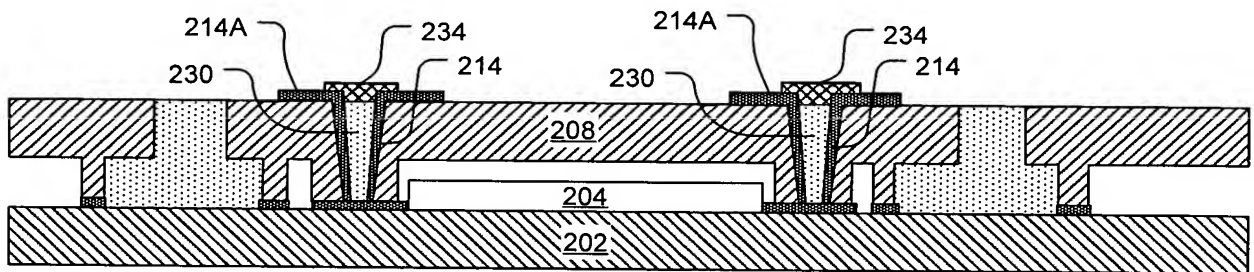


Fig. 5

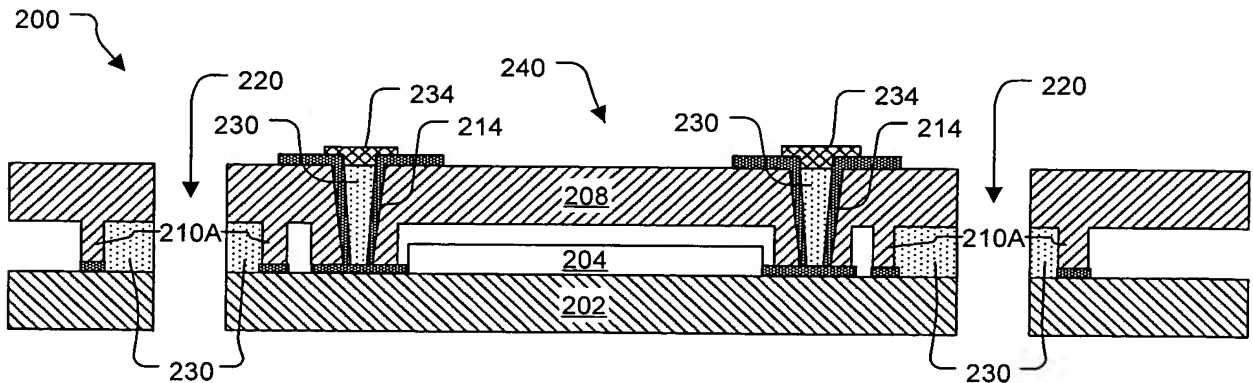


Fig. 6

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4/5

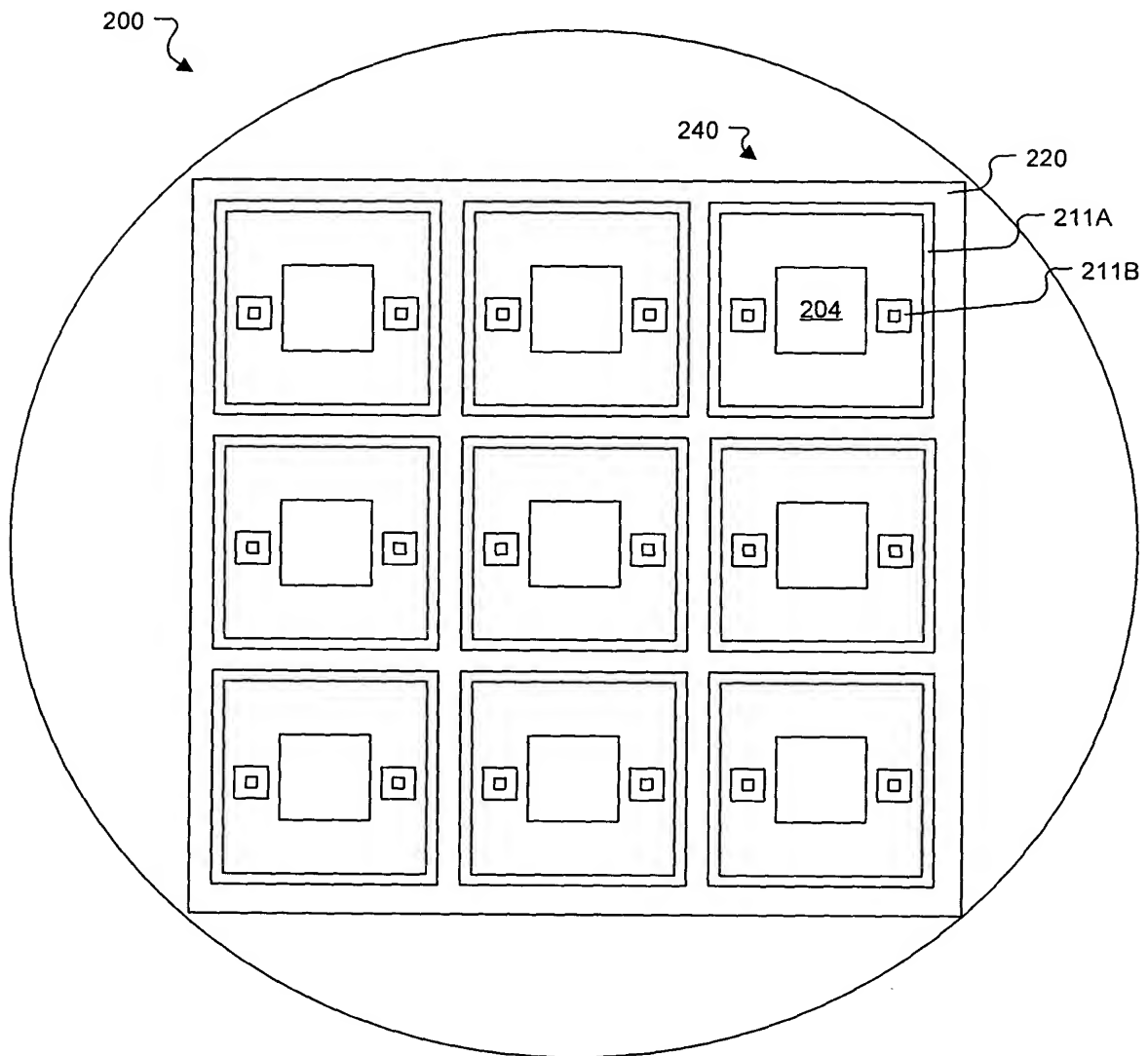


Fig. 7

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Docket no.: 10030302-1

5/5

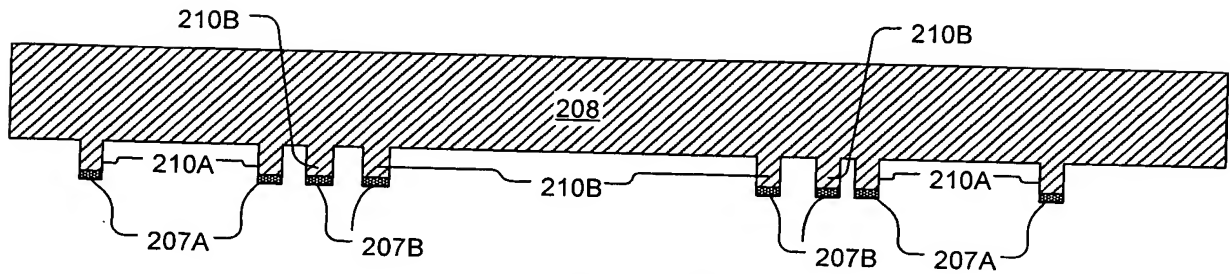


Fig. 8

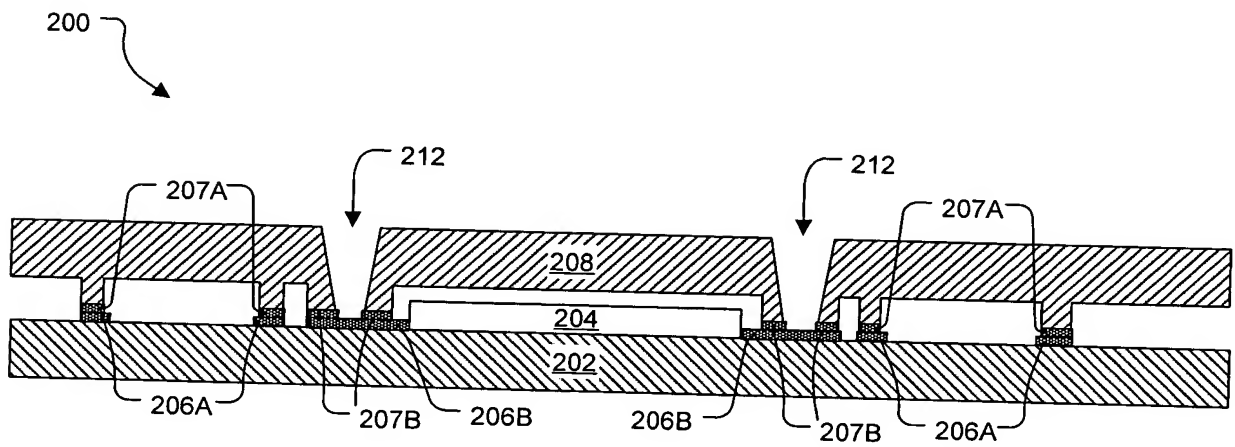


Fig. 9